

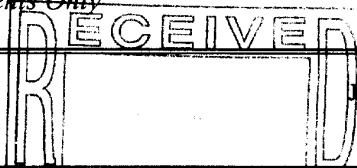
ASSIGNMENT RECORD

06-17-1998



100742037

Patents Only

June 1, 1998
5649.503

To the Honorable Commission

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Nam-jung Hur
Yong-hwan Kwon
Jong-han Park

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.
416 Mactan-dong
Paldal-gu, Suwon-city
Kyungki-do, Republic of KoreaAdditional name(s) of conveying party(ies) attached? ___ Yes ☒ No

3. Nature of conveyance:

☒ Assignment
___ Merger
___ Security Agreement
___ Change of Name
___ Other _____

Execution Date: January 19, 1998

Additional name(s) & address(es) attached? ___ Yes ☒ No4. Application Serial No. 09/063,716, filed April 21, 1998 Patent No.If this document is being filed together with a new application, the execution date of the application
is:Additional numbers attached? ___ Yes ☒ No5. Name and address of party to whom correspondence
concerning document should be mailed:Mitchell S. Bigel, Esq.
Myers Bigel Sibley & Sajovec
P. O. Box 37428
Raleigh NC 276276. Total number of applications and patents involved: 17. Total fee (37 CFR 3.41) \$40.00
☒ Enclosed
___ Authorized to be charged to deposit account

8. Deposit account number:

DO NOT USE THIS SPACE

9. Statement and signature

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy
of the original document.*Mitchell S. Bigel, Reg. No. 29,614

Name of Person Signing

Signature

June 1, 1998

Date

Total number of pages including cover sheet, attachments and document: 3

06/16/1998 TTOM11 00000236 09063716

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40.00 OP

PATENT
REEL: 9238 FRAME: 0533

ASSIGNMENT

THIS ASSIGNMENT, made by us, Nam-jung Hur, Yong-hwan Kwon and Jong-han Park, all citizens of the Republic of Korea, all residing at San 24, Nongseo-ri, Kiheung-eub, Yongin-city, Kyungki-do, Republic of Korea

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in **SILVER-TIN ALLOY SOLDER BUMPS AND METHODS OF FABRICATING AND TESTING THE SOLDER BUMPS** for which an application for United States Letters Patent has been filed in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, L.L.P., to insert here in parentheses (Application No. 09/063,716, filed April 21, 1998) the filing date and application number of said application when known, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-City, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;


NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

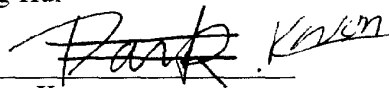
We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

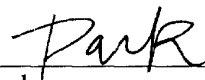
IN WITNESS WHEREOF, we have hereunto set our hands and seals on this 19th day of January, 1998.



Nam-jung Hur

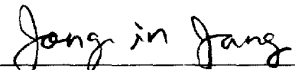


Yong-hwan Kwon



Jong-han Park

Witnessed by:



Jong-in Jang

Date: 1/19, 1998



J. Aery

Date: 1/19, 1998